

## N-Channel Enhancement Mode Power MOSFET

### Description

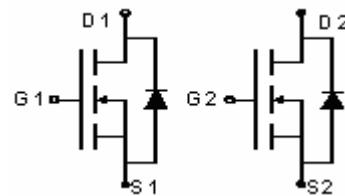
The PE4946 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

- $V_{DS} = 60V, I_D = 4.5A$
- $R_{DS(ON)} < 45m\Omega @ V_{GS}=10V$  (Typ:  $38m\Omega$ )
- High density cell design for ultra low  $R_{dson}$
- Fully characterized avalanche voltage and current
- Low gate to drain charge to reduce switching losses

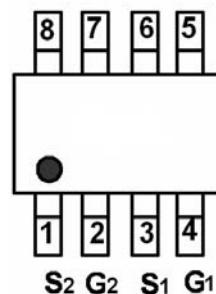
### Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

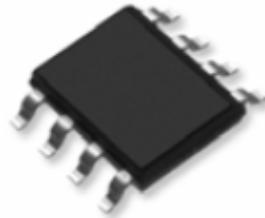


Schematic diagram

D<sub>2</sub> D<sub>2</sub> D<sub>1</sub> D<sub>1</sub>



Marking and pin assignment



SOP-8 top view

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	4.5	A
Drain Current-Continuous( $T_C=100^\circ C$ )	$I_D (100^\circ C)$	3.0	A
Pulsed Drain Current	$I_{DM}$	20	A
Maximum Power Dissipation	$P_D$	2	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

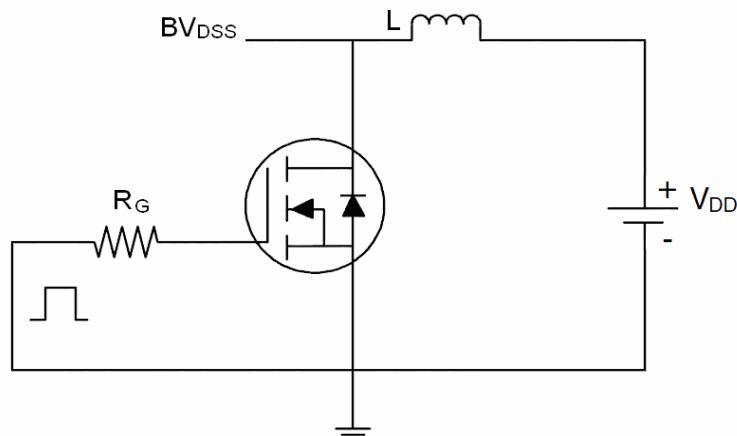
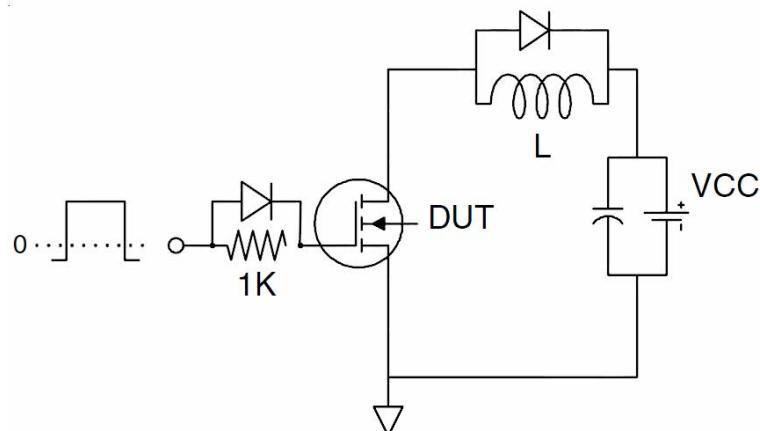
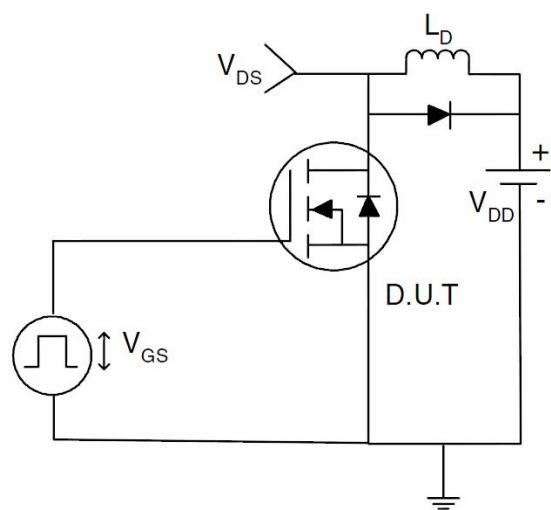
Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	62.5	°C/W
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**Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

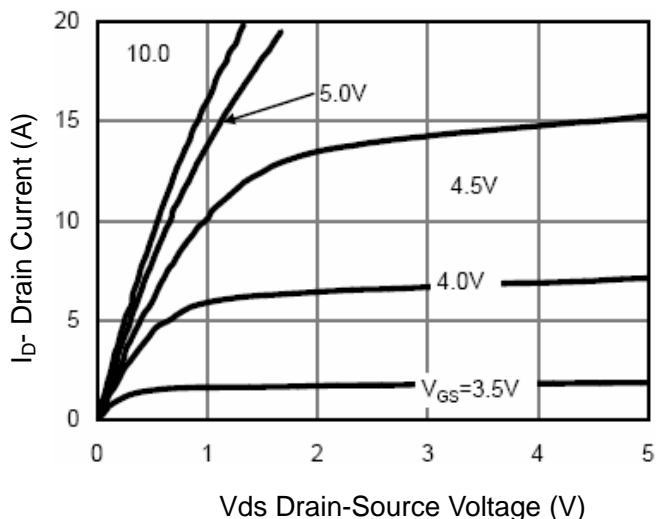
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	69	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	2.0	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=4.5\text{A}$		38	45	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=4.5\text{A}$	11	-	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$		450		PF
Output Capacitance	$C_{\text{oss}}$			60		PF
Reverse Transfer Capacitance	$C_{\text{rss}}$			25		PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=4.5\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$	-	4.7	-	nS
Turn-on Rise Time	$t_r$		-	2.3	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	15.7	-	nS
Turn-Off Fall Time	$t_f$		-	1.9	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=4.5\text{A}, V_{\text{GS}}=10\text{V}$	-	8.5	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	1.6	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	2.2	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=3.7\text{A}$	-	-	1.2	V
Diode Forward Current (Note 2)	$I_{\text{s}}$		-	-	4	A

**Notes:**

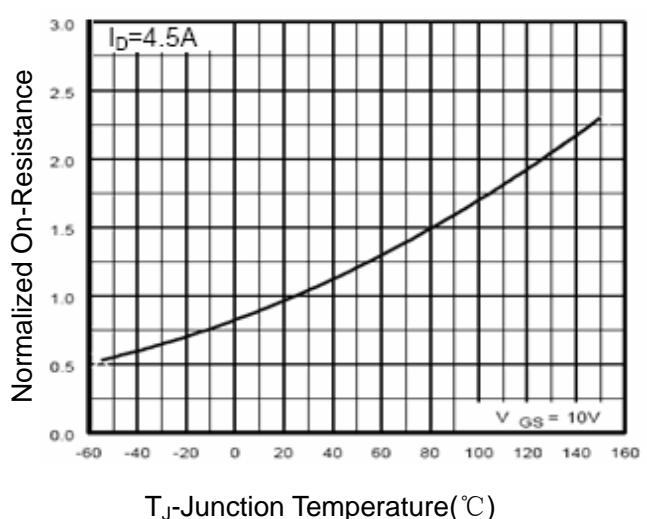
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

**Test Circuit****1) E<sub>AS</sub> test Circuits****2) Gate charge test Circuit****3) Switch Time Test Circuit**

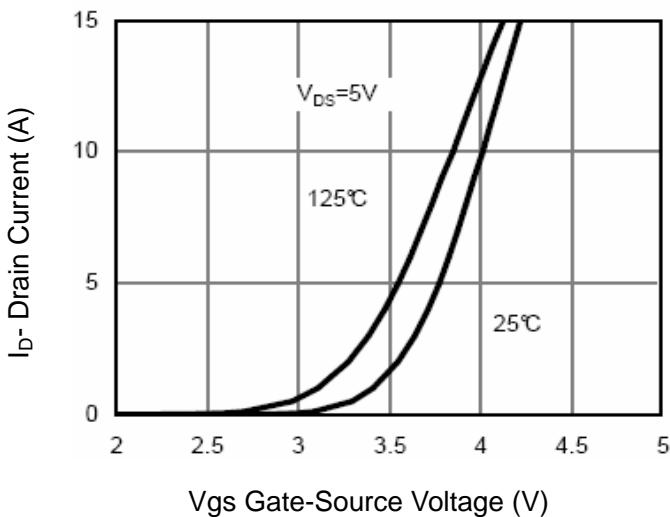
### Typical Electrical and Thermal Characteristics (Curves)



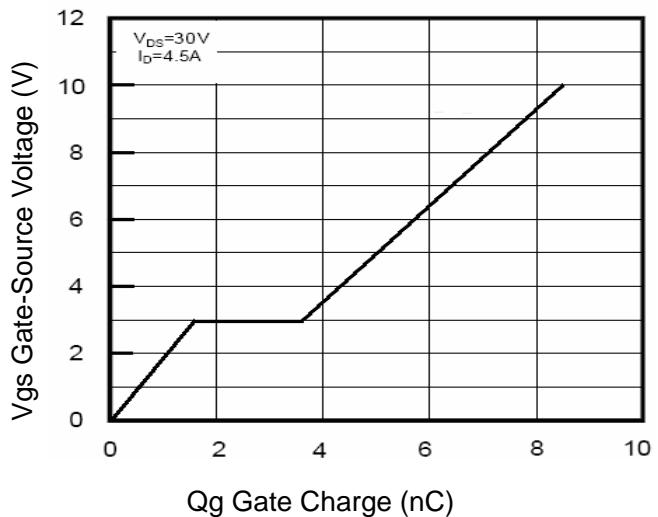
**Figure 1 Output Characteristics**



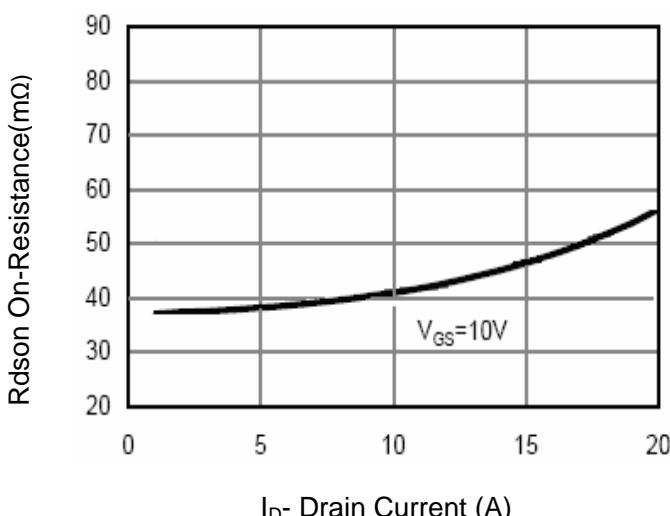
**Figure 4 Rdson-JunctionTemperature**



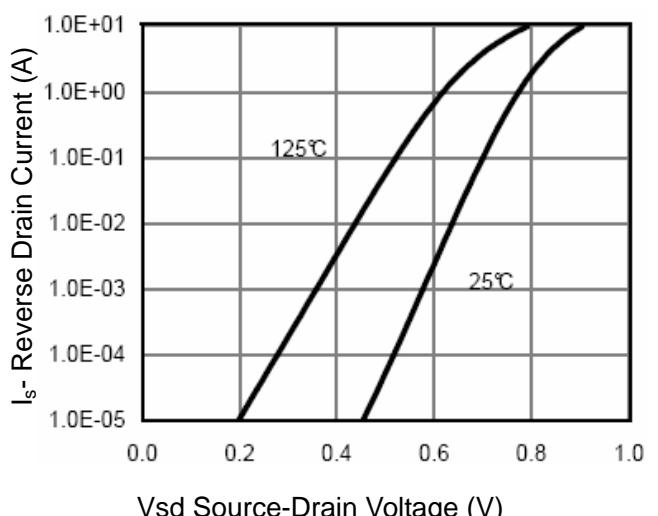
**Figure 2 Transfer Characteristics**



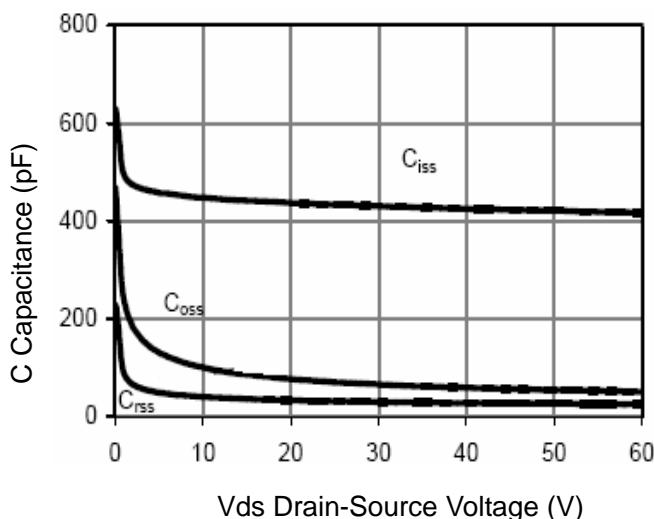
**Figure 5 Gate Charge**



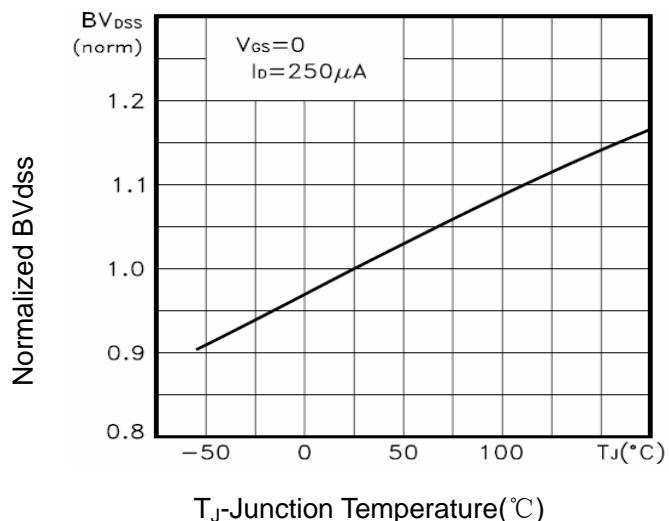
**Figure 3 Rdson- Drain Current**



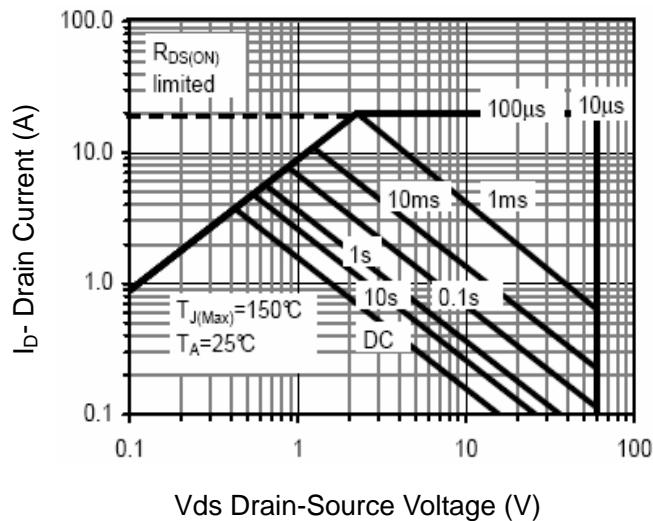
**Figure 6 Source- Drain Diode Forward**



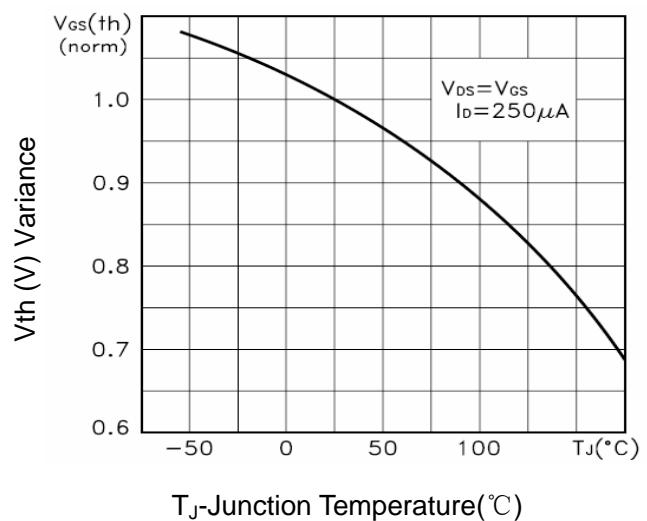
**Figure 7 Capacitance vs Vds**



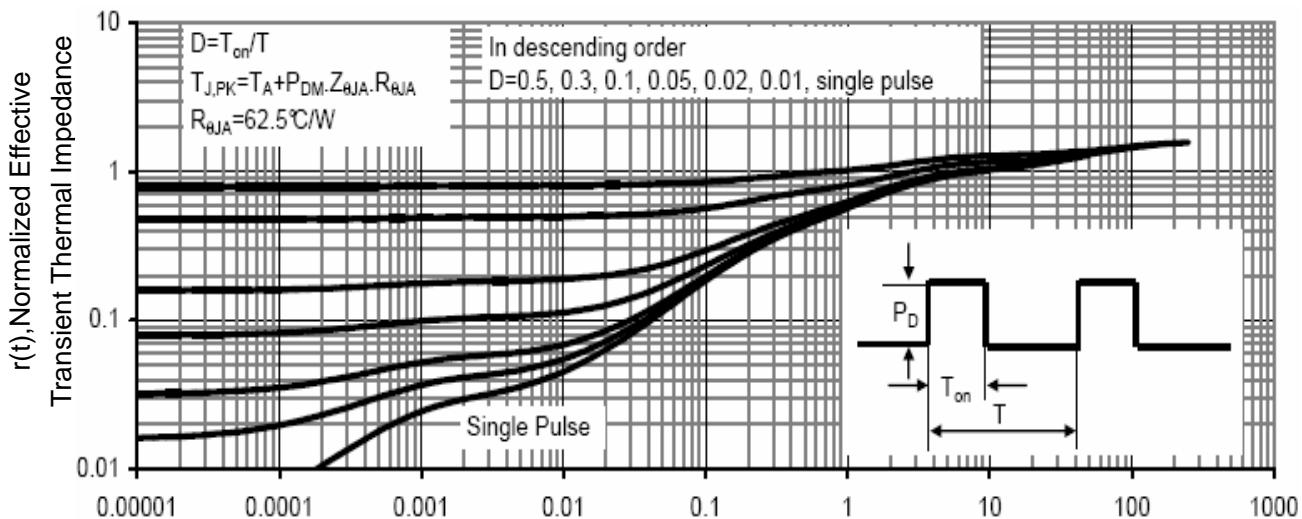
**Figure 9  $BV_{dss}$  vs Junction Temperature**



**Figure 8 Safe Operation Area**

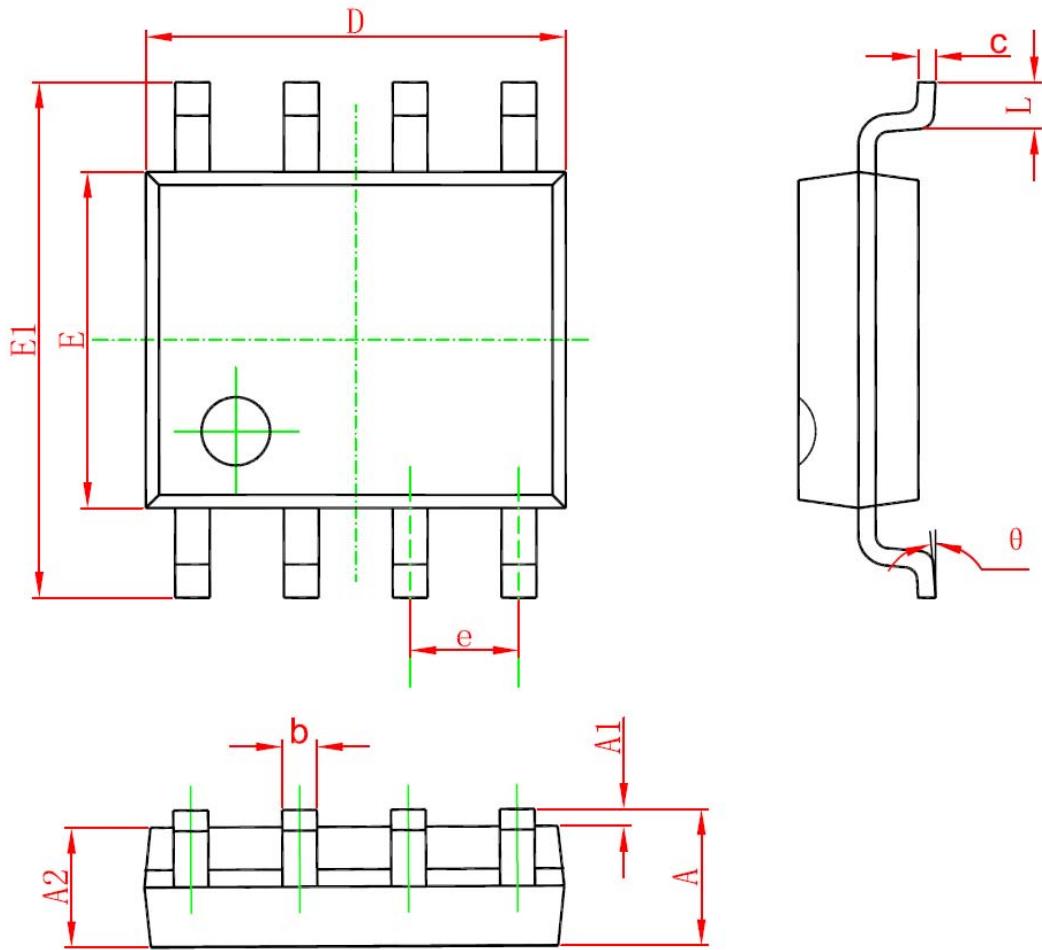


**Figure 10  $V_{GS(\text{th})}$  vs Junction Temperature**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°